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Institute of High Energy Physics Chinese Academy of Sciences

Study of the HVCMOS detector

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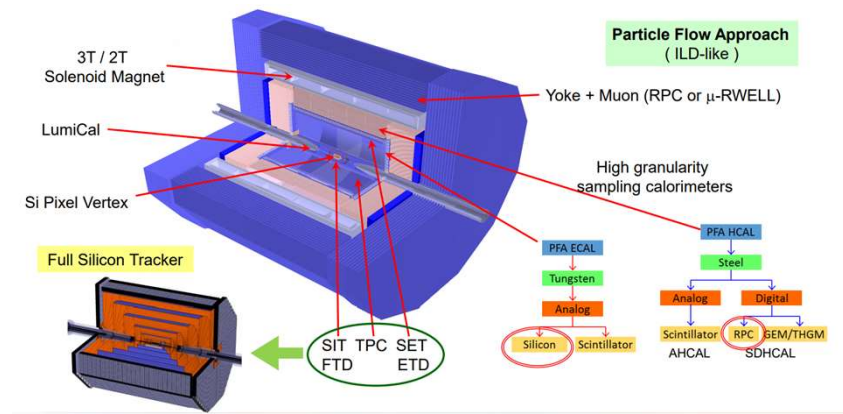
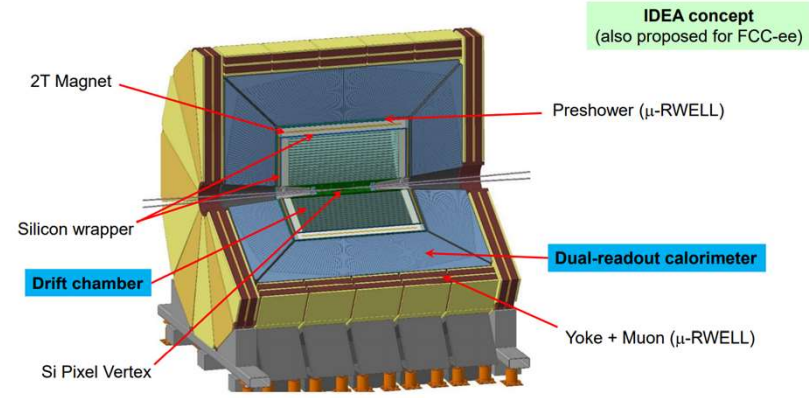
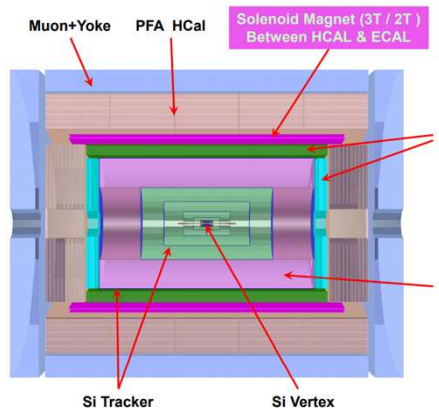
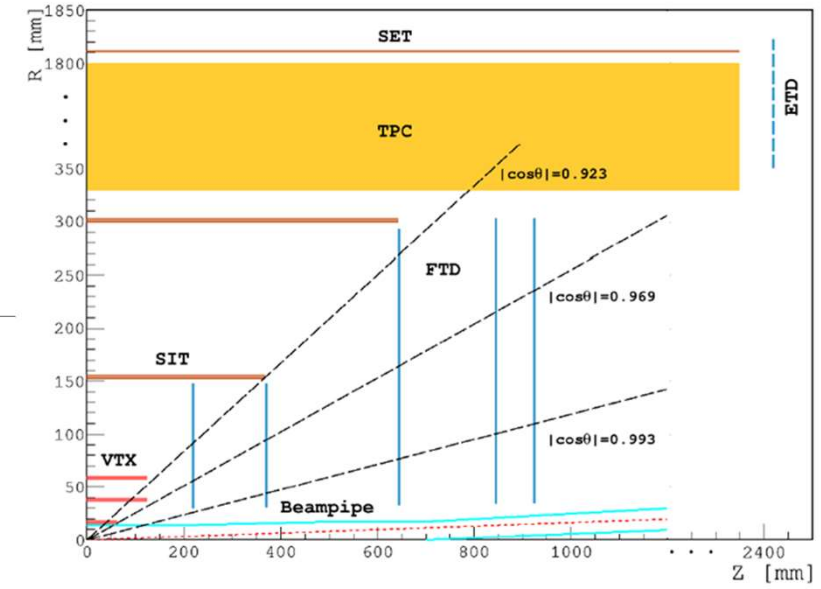
Content

- Background: CEPC silicon tracker
- High Voltage CMOS detector
- A HV CMOS Chip:AtlasPIX3
- Test System: hardware and software
- Test Procedure: Test in the lab
- Radioactive Source Test
- Application: Test with beam
- Future Plan: Multi-Chip Module



Background

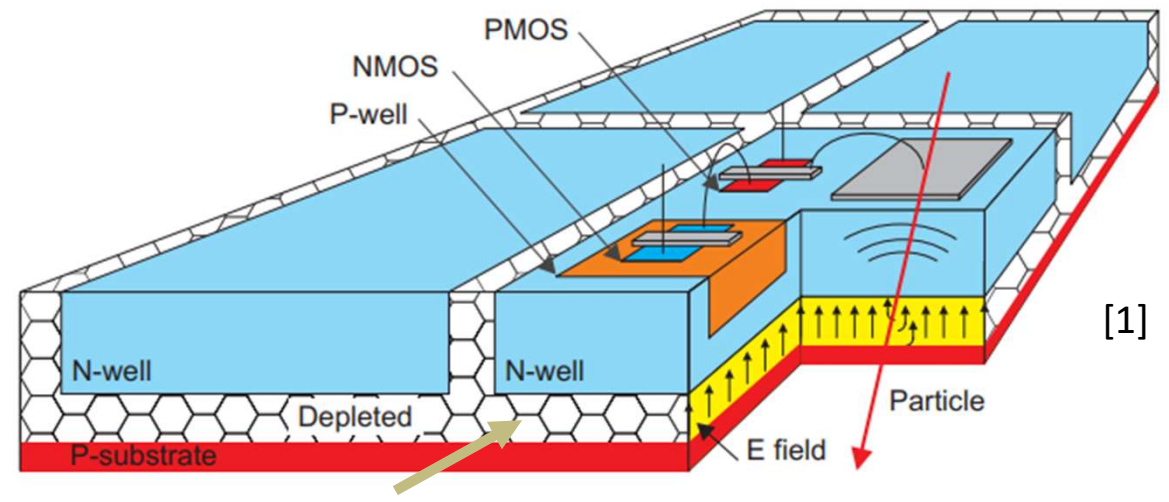
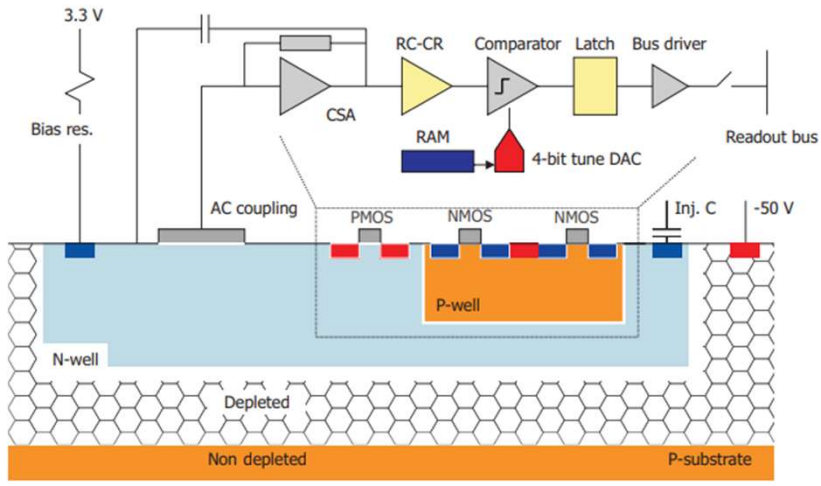
- CEPC Tracker:
 - outside of the VTX
 - TPC/DC + silicon or all-silicon concepts





HV CMOS detector

- Detection based on the charge drift in the depleted zone of the reverse biased diode.
- Depleted zone thickness about $10\mu\text{m}$ (60V)
- Depleted area one magnitude larger than LV CMOS



About $10\mu\text{m}$



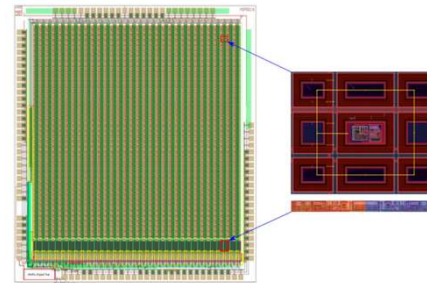
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Features of HVCMOS

- Good performance on efficiency(99.5%)
- Low noise(lower than 1Hz threshold above 50mV)
- Good time resolution(lower than 10ns)
- Fast charge collection
- Good radiation tolerance(High efficiency >98% at up to $2 \times 10^{15} n_{eq}/cm^2$)

Examples



MuPIX7

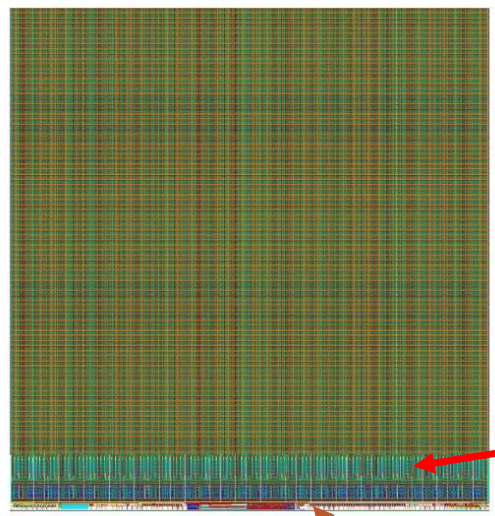
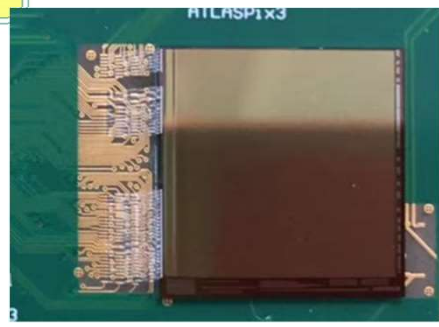
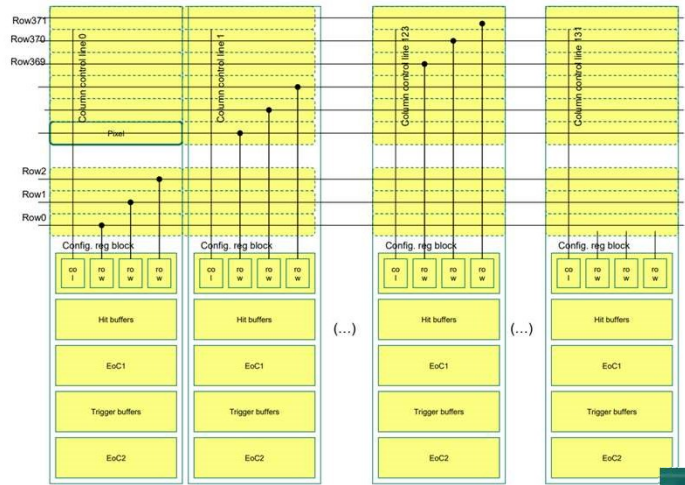


ATLASPIX3



ATLASPIX3

- 372col × 132row
 - 150 × 50μm per pixel
 - About 2cm × 2cm in total
 - TSI 180 nm process on 200 Ω cm substrate
 - High efficiency 99.5%
 - High radiation tolerance
- (High efficiency >98% at up to $2 \times 10^{15} n_{eq}/cm^2$)



pixels

Config register block

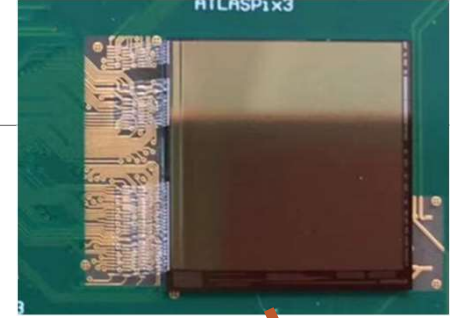
Hit buffer, trigger buffer and EoC blocks



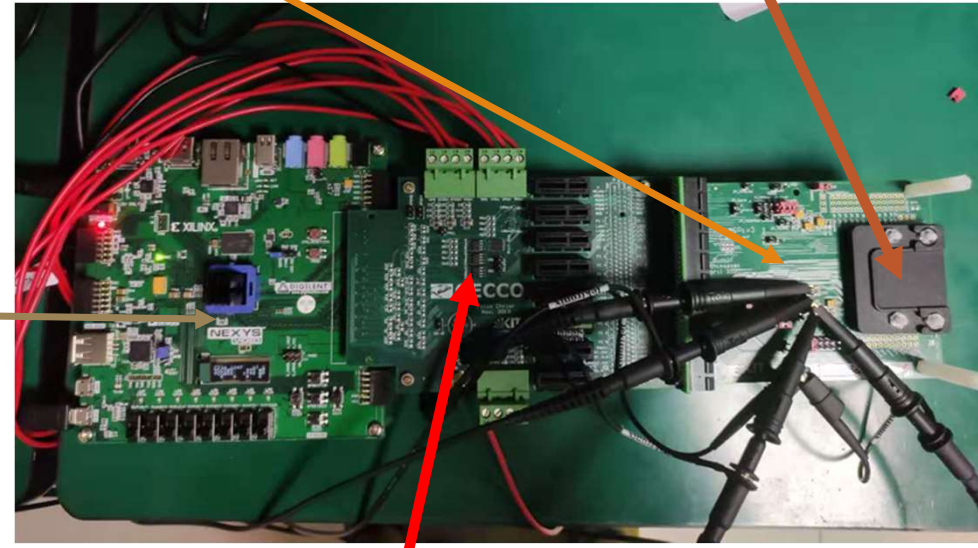
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Test System: Hardware

Chip Carrier board(KIT)

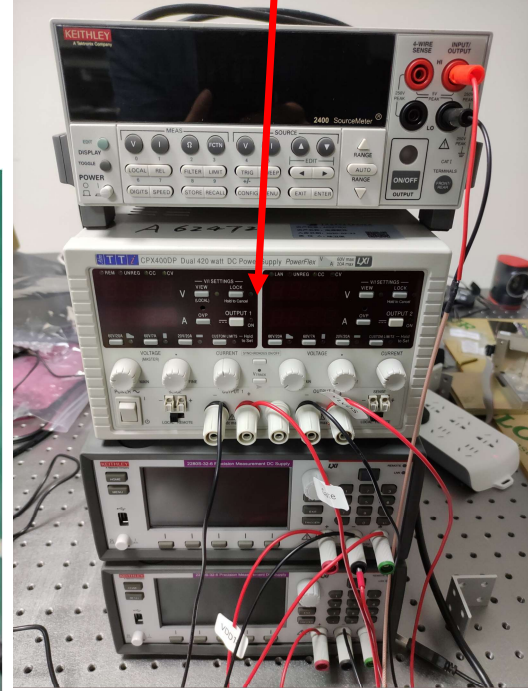


NexysVideo FPGA



GECCO board

4-Channal Power Supply



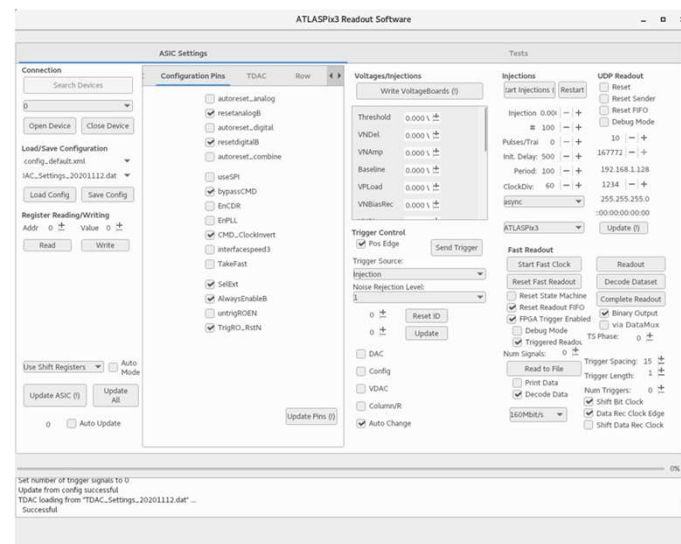
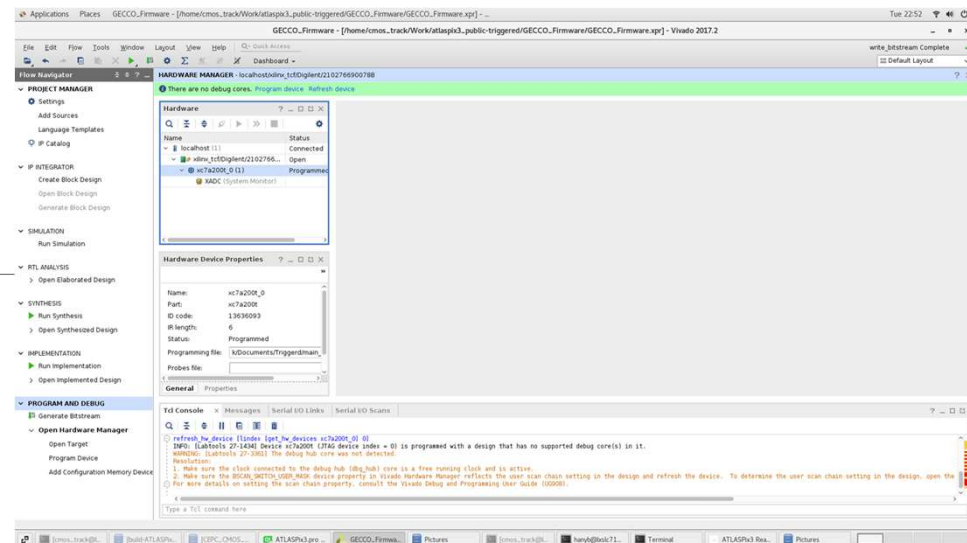


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Test Software

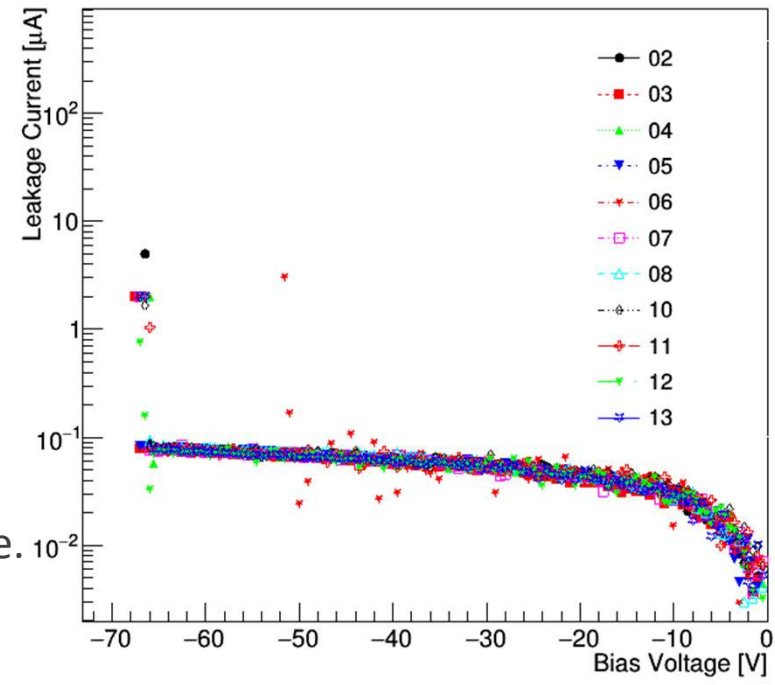
- Vivado(Configure Firmware):
 - Compile&Configure Firmware(**Rudolf,KIT**)
- DAQ Software(**Rudolf,KIT**):
 - Connect with the FPGA board
 - Configure Chip registers
 - Fast Readout Test
 - Scan S-curve(Check Threshold)
 - Trimming the chip(Adjust Threshold)





Test in lab: HV Bias Voltage Test

- Change HV Voltage and get an IV curve
- To check the HV leakage current & Breakdown voltage
 - Break voltage at about -65V
 - Leakage current: about 50nA@-20V at room temperature.



IV curve of several chips

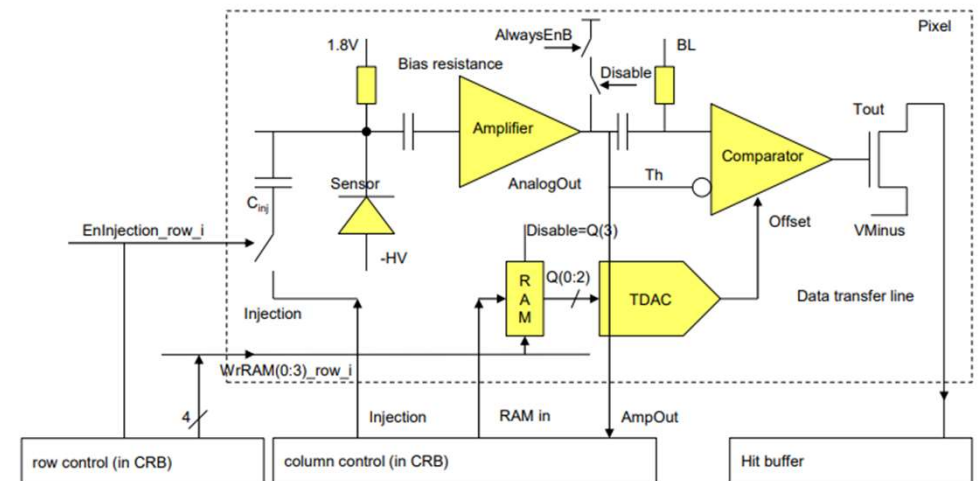
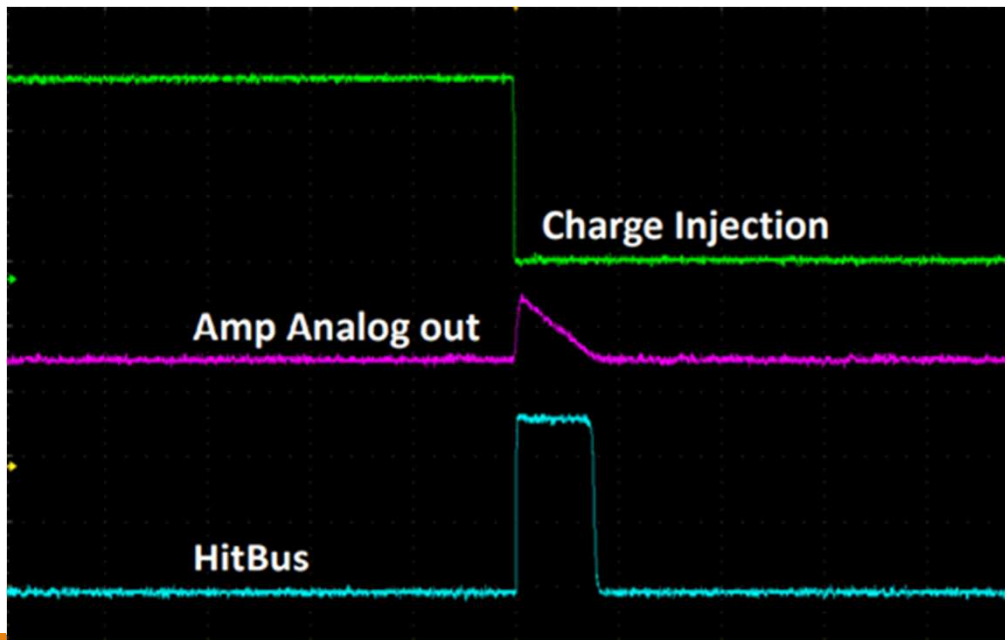
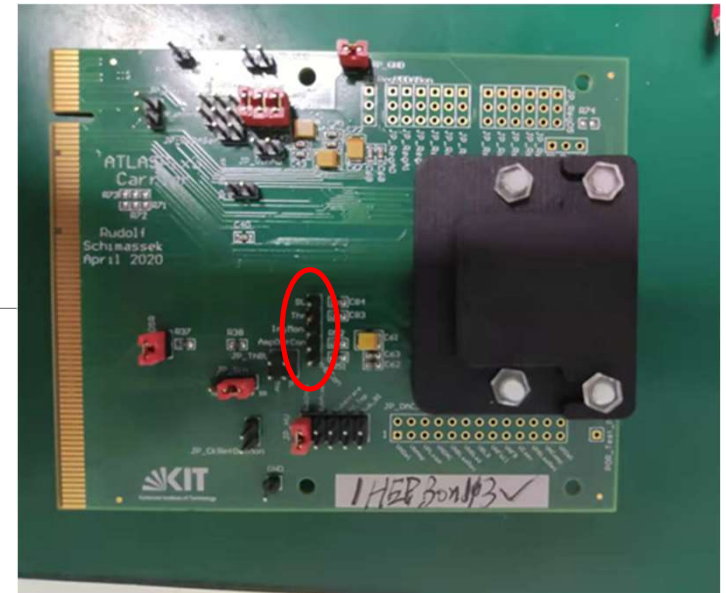


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Analog Signal Test

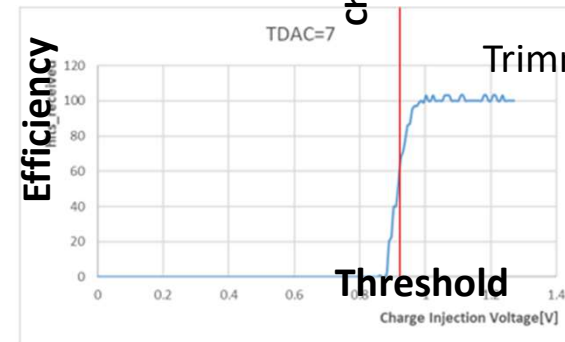
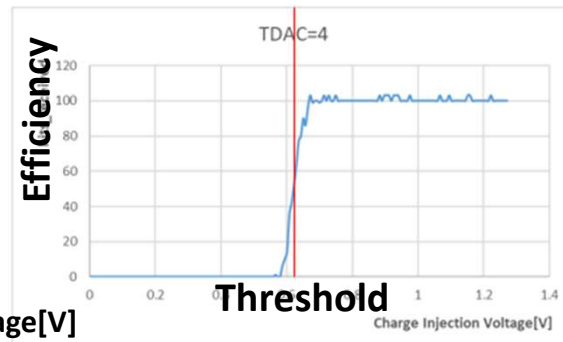
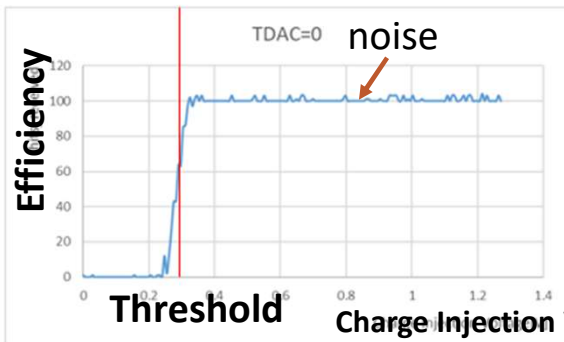
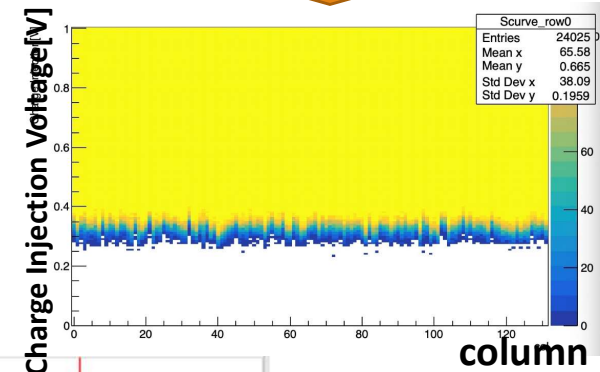
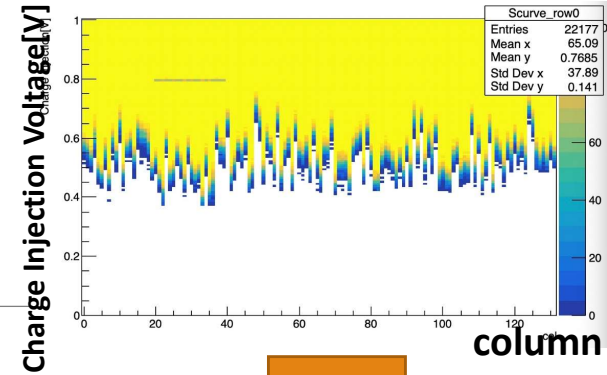
- Use Oscilloscope to measure 5 pins on chip carrier board
- To check and make sure the readout works well





Trimming Test

- Threshold : S-curve(Efficiency 0%→100%)
- Trimming Procedure :
 - Measure S-curves of all pixels
 - Threshold distribution
 - TDAC optimization(minimize sigma)
- After trimming, threshold perform similar in different pixels



Trimming performance

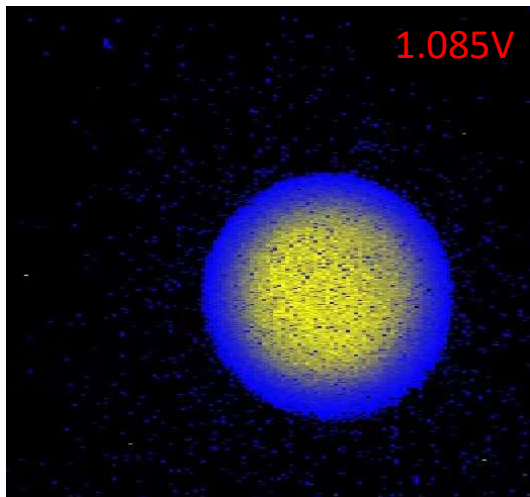


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Radioactive Source Test: Fe55 (5.9keV EC)

- To calibrate the Threshold with Energy
- Tape the source at the back side of the chip (with collimation)



Calibrate the Fe55 5.9keV with threshold 1.085V





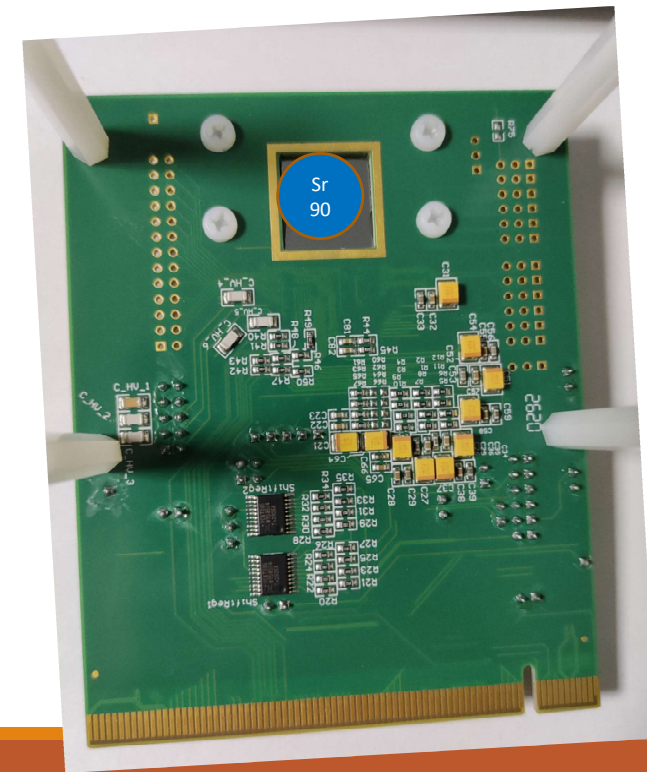
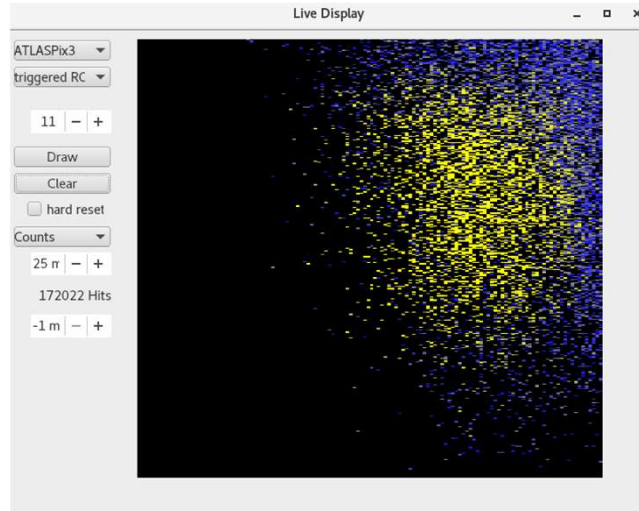
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Radioactive Source Test: Sr90 (546keV, β^-)

- Can be detected at higher Threshold
- Use a collimation to have a circle shape
- Tape to the back side of the chip

- Read the Hitmap

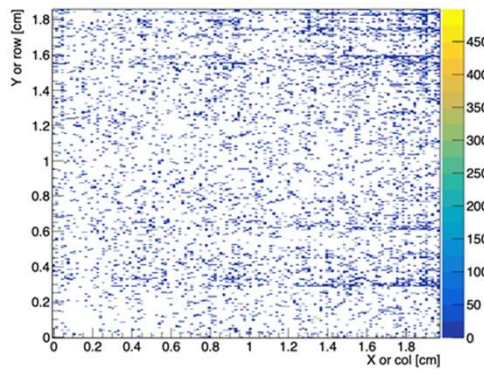




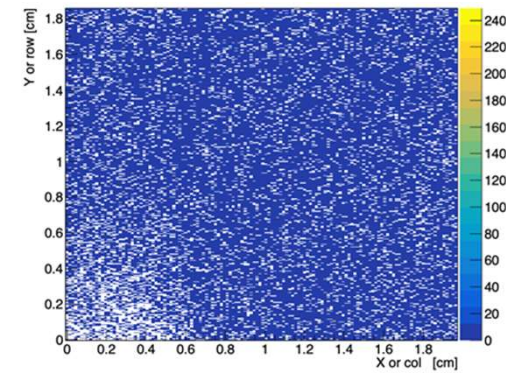
Application : Test with Electron beam

AtlasPIX3 Chip

- Detect the Electron and X-ray in the beam
- Electron and X-ray(>6.9keV) can be detected
- When Magnet on, the electron beam will turn

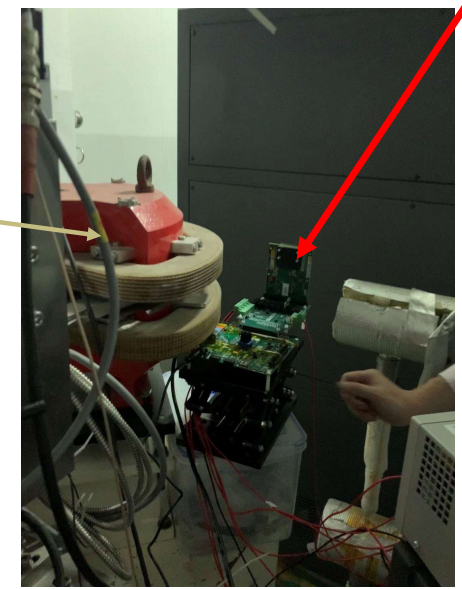


Magnet Off(X-ray)
(Disable electron)



Magnet On(e- and X-ray)
(Enable electron)

Beam direction



- When Magnet off, there are still hits, which are recognized as X-ray.

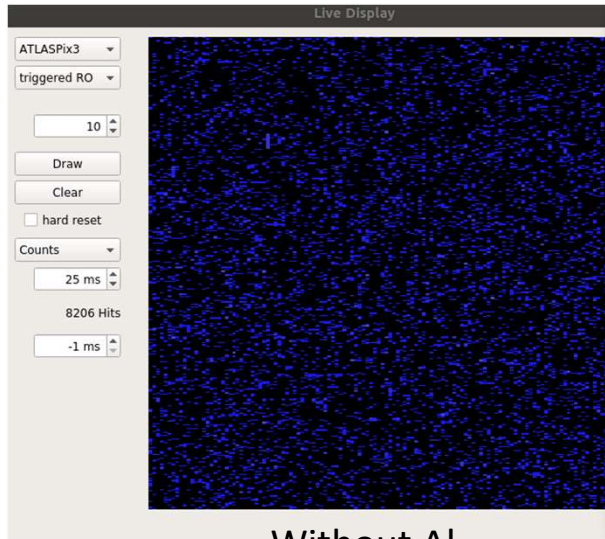
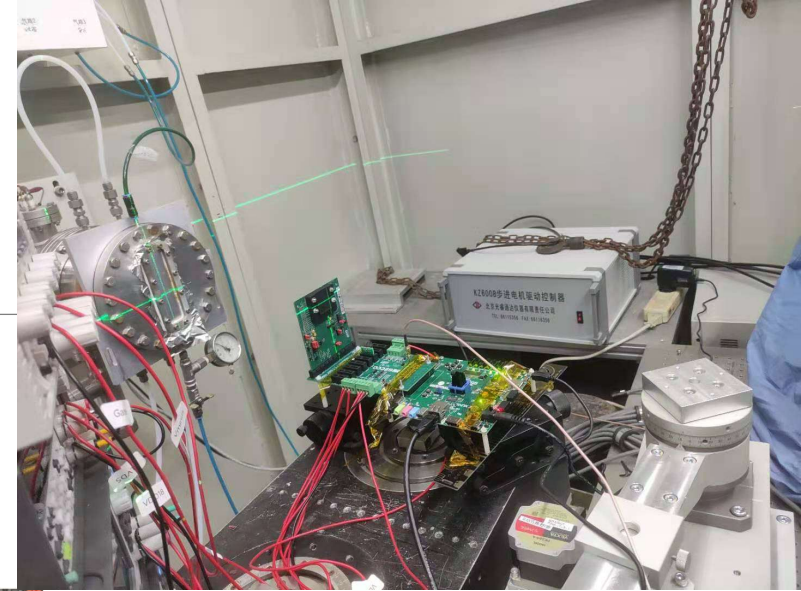


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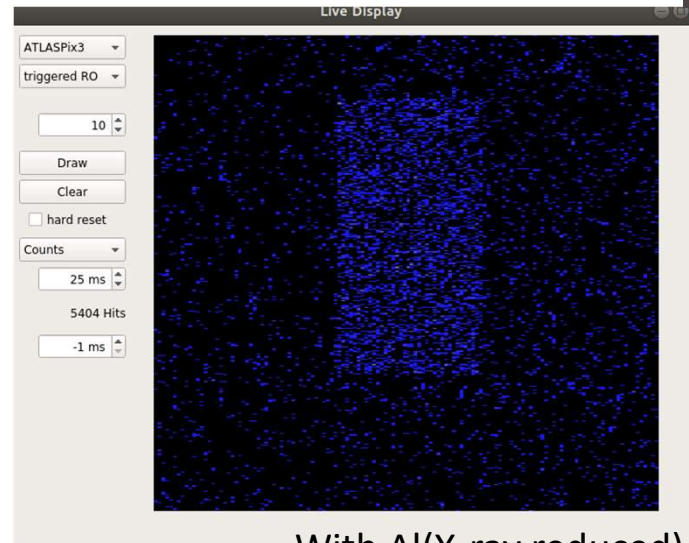
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Test with synchrotron X-ray

- Beam open a little rectangle window/shutter
- An Aluminum foil can be placed to shield the X-ray
- Al shield X-ray, electron obvious at the rectangle



Without Al



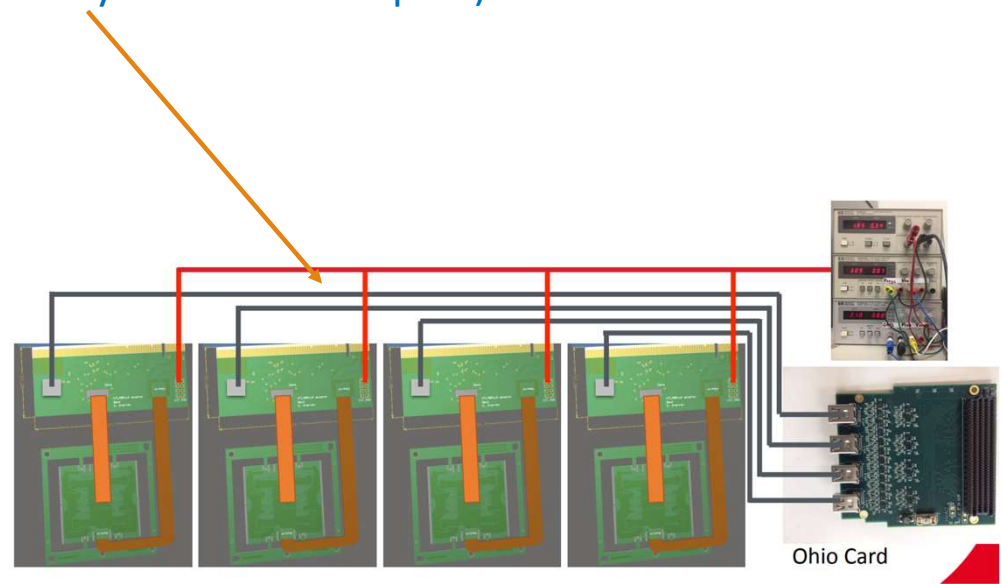
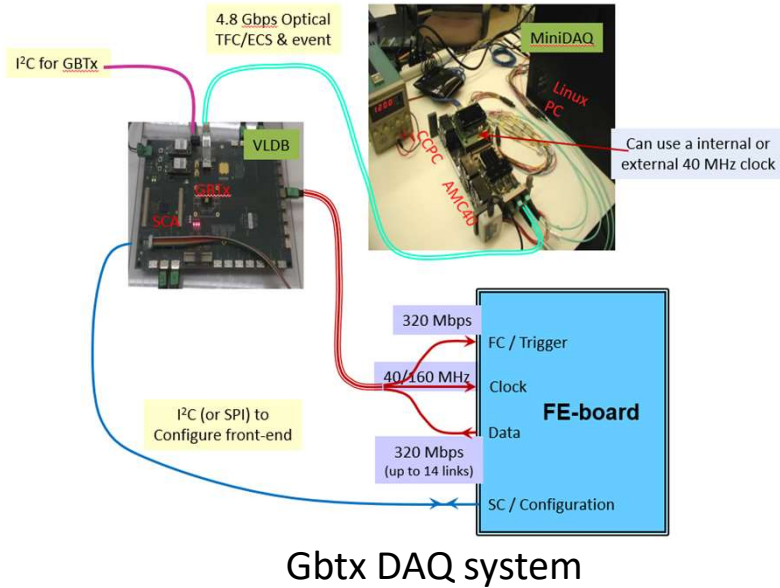
With Al(X-ray reduced)



Future Plan

- Multi-chip Module readout test:

- YARR(Yet A Rapid Readout)(H .Fox Wednesday afternoon's report)
- DAQ system based on GBTx(LHCb)



YARR

Summary

- HV CMOS silicon tracker simple introduction
- ATLASPix3 tested in lab and works well
- Test with radioactive source Fe55 and Sr90
- Application with electron beam and synchrotron radiation
- Future plan: multi-chip module readout

Thanks for your attention!

Thanks!

backups

GECCO – The Concept

- **GE**neric **C**onfiguration and **CO**ntrOl System
- It is a collection of
 - hardware
 - firmware
 - softwarefor testing ASICs
- central element: the GECCO board
- Design Goals:
 - versatile for application with different chips
 - easy change of sample
 - enable hands-free debugging
 - economic



GECCO





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Test Process: Power Supply

- Basically, it needs 7-channel power supply.
- While using on-board regulators, only 4-channel power supply.
- To save space , use less power supply

